TE Internal #: 2198235-3

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, Internal/External EMI Springs, SFP+ Enhanced, Not Optional, 1 x 6,

Through Hole - Press-Fit

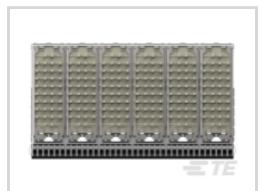
View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+











Pluggable I/O Product Type: Cage Assembly

Data Rate (Max): 16 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Pluggable I/O Applications: SFP+ Enhanced

Lightpipe Options: Not Optional

Features

Product Type Features

| Form Factor | SFP+ |
|---------------------------------------------------|------------------------------|
| Cage Type | Ganged |
| Thermal Accessory Type Included | Heat Sink |
| Pluggable I/O Product Type | Cage Assembly |
| Lightpipe Options | Not Optional |
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | |
| Connector & Contact reminates 10 | Printed Circuit Board |
| Configuration Features | Printed Circuit Board |
| | Printed Circuit Board 1 x 6 |
| Configuration Features | |
| Configuration Features Port Matrix Configuration | 1 x 6 |

16 Gb/s

Data Rate (Max)



| Heat Sink Height Class | Networking Short |
|---------------------------------------------|----------------------------|
| Heat Sink Height | 9.1 mm[.358 in] |
| Heat Sink Style | Pin |
| Termination Features | |
| Termination Post & Tail Length | 2.05 mm[.081 in] |
| Termination Method to Printed Circuit Board | Through Hole - Press-Fit |
| Mechanical Attachment | |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Cage Material | Nickel Silver |
| Dimensions | |
| PCB Thickness (Recommended) | 2.25 mm[.089 in] |
| Usage Conditions | |
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
| Operation/Application | |
| Heat Sink Compatible | Yes |
| For Use With Pluggable I/O Products | SFP+ SMT Connector |
| Pluggable I/O Applications | SFP+ Enhanced |
| Circuit Application | Signal |
| Packaging Features | |
| | |
| Packaging Method | Box & Tray, Package |
| Packaging Method Other | Box & Tray, Package |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|-----------------------------------------------|-----------------------------------------------------------------------------------------------|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) |



| $D_{\alpha\alpha\alpha}$ | n 0+ | aantain | REACH | CV/LIC |
|--------------------------|------|---------|-------|--------|
| Does | not | contain | KEACH | SVHU |

| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per |
|-----------------|------------------------------------------|
| | homogenous material. Also BFR/CFR/PVC |
| | Free |

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





TE Part # CAT-C11-H50626 SFP+ to SFP+ I/O Cable Assembly: 30 AWG



30 AWG







AWG

















TE Part # CAT-C11-H506 SFP+ to SFP+ I/O Cable Assembly: 26 AWG



TE Part # CAT-C11-H5062 SFP+ to SFP+ I/O Cable Assembly: 28 AWG



TE Part # 2334985-2 SFP28 DIRECT ATTACH CA, 1M, 32AWG



TE Part # 2142970-1 CABLE ASSY, MICRO SFP+ TO STD SFP+, 0.5M



TE Part # 2142970-2 CABLE ASSY, MICRO SFP+ TO STD SFP+, 1M



TE Part # 2142970-3 CABLE ASSY, MICRO SFP+ TO STD SFP+, 2M



TE Part # 2142970-4 CABLE ASSY, MICRO SFP+ TO STD SFP+, 3M



TE Part # 2142970-5 CABLE ASSY, MICRO SFP+ TO STD SFP+, 4M

Customers Also Bought



TE Part #5787962-1
.8MM CHAMP STACK RCPT ASSY



TE Part #1658945-1 XFP CAGE ASSY w/o ELASTOMERIC GASKET



TE Part #2169851-1 Heat Sink Clip, Ganged SFP+



TE Part #6-1761612-0 STEP-Z PLUG 10MM 104P LF ST



TE Part #2118016-2
PCB ANTENNAS, WLAN DUAL BAND
T&R PKG

TE Part #1645680-1
ZP HS3 DB 06R REC 030P RE PD

TE Part #1645681-1
ZP HS3 DB 06R REC 030P LE PD

TE Part #1888251-5 Low Profile,RJ45,1x4,Bi-Color

TE Part #2270299-4
PV4-S F TO MC4 M JUMPER CABLE
150MM

Documents



Product Drawings

SFP+ Enhanced 1x6, Networking Heatsink

English

CAD Files

Customer View Model

ENG_CVM_CVM_2198235-3_A.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2198235-3_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2198235-3_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English